r Reference: ESI-116-B

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

licant:

Patrick F. Leonard

Serial No.

09/680,342

Filing Date:

October 5, 2000

Examiner/Art Unit

C. Kao

Title:

METHOD AND APPARATUS FOR EVALUATING

INTEGRATED CIRCUIT PACKAGES HAVING THREE

DIMENSIONAL FEATURES

AMENDMENT

BOX AF

Assistant Commissioner of Patents Washington, D.C. 20231

Sir:

AMENDIMENT

missioner of Patents

D.C. 20231

The Final Office Action dated January 2, 2003 has been received and carefully reviewed. Please amend the above-identified patent application as indicated below.

In the claims:

17. (Amended) A method for evaluating the quality of an IC package where the IC package includes a plurality of three dimensional features, the method comprising: acquiring a two dimensional image characteristic of a portion of the IC package, the two dimensional image defined by a plurality of pixels having at least an address and a pixel intensity;

acquiring a three dimensional image characteristic of the portion of the IC package, the three dimensional image defined by a plurality of pixels having at least an address and an altitude;

processing the two dimensional image to identify a plurality of addresses which are characteristic of three dimensional features;

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